

Integrated Device Technology, Inc. 6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

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	DATE: 29-Jul-2016	1_	NGUISHING CHANGED DEVICES:					
Product Affected: 15.0mm x 15.0mm FC		☐ Product Mark						
24.0mm x 15.5mm FC		☐ Back Mark						
Refer to Attachment II for the affe	ected part numbers	Date Code	Assembly lot marked on the device					
		■ Other	provides traceability to the material used					
Date Effective: 11-Jul-2016			uscu					
Contact: IDT PCN DESK		Attachment:	Yes No					
E-mail: pcndesk@idt.com		Samples: Please contact your local sales representative for sample request & availability.						
DESCRIPTION AND PURPOSE OF CHA	ANGE:							
☐ Die Technology	Revision 1: This revise	ed notice is to advise	customers that the lid adhesive material					
□ Wafer Fabrication Process□ Assembly Process		d as MD140. Henkel CE-3920 is added as an alternate material.						
☐ Equipment ■ Material	There is no change to the moisture performance.							
☐ Testing	Attachment I details the	e qualification data fo	or this change and					
☐ Manufacturing Site	Attachment II shows th							
☐ Data Sheet ☐ Other								
- Oulei								
RELIABILITY/QUALIFICATION SUM								
Refer to qualification data shown in attachn	nent 1.							
CUSTOMER ACKNOWLEDGMENT O	F RECEIPT:							
IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail								
to grant approval or request additional infor it will be assumed that this change is accept		receive acknowledge	ment within 30 days of this notice					
IDT reserves the right to ship either version		process change effect	ive date until the inventory					
on the earlier version has been depleted.		r8						
Customer:] Approval for s	shipments prior to effective date.					
Name/Date:	E-	Mail Address:						
Title:		none# /Fax# :						
CUSTOMER COMMENTS:								
IDT ACKNOWLEDGMENT OF RECEI	PT:							
RECD. BY:		DATE:						



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ATTACHMENT I - PCN #: A1603-01 (R1)

PCN Type: Adding Alternate Materials

Data Sheet Change: None

No change in moisture sensitivity level (MSL)

Detail Of Change:

<u>Revision 1:</u> This revised notice is to advise customers that the lid adhesive material will remain unchanged as MD140. Henkel CE-3920 is added as an alternate material.

There is no change to the moisture performance of these packages.

Change of Material Set

Description	From	То
Lid Adhesive Material	MD140	MD140 and Henkel CE-3920 (alternate)

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ATTACHMENT I - PCN #: A1603-01'*T3+

Qualification Test Plans and Results:

Qual Plan & Results: The qualification was performed in accordance with JEDEC47 recommended

tests

Qual Vehicle: 15.0mm x 15.0mm FCBGA-196 (1 lot)

24.0mm x 15.5mm FCBGA-345 (2 lots)

			Test Results (SS / Rej)		
Test Description	Test Method	Lot 1	Lot 2	Lot 3	
* HAST - Unbiased (130 °C/85% RH, 96 Hrs)	JESD22-A118	25/0	25/0	25/0	
* Temperature Cycle / Condition B (-55 °C to +125 °C, 700 Cyc)	JESD22-A104	25/0	25/0	25/0	
High Temp. Storage Test (150 °C, 1000 Hrs)	JESD22-A103	25/0	25/0	25/0	

Note:

^{*} Test requires moisture pre-conditioning sequence per JESD22-A113 prior to stress test

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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT II - PCN #: A1603-01'*T3+

Affected Part Numbers

Part Number	Part Number	Part Number	Part Number
89HT0816APZCBLG	89HT0816APZCBLGI	89HT0832PZCBLG	89HT0832PZCBLGI
89HT0816APZCBLG8	89HT0816APZCBLGI8	89HT0832PZCBLG8	89HT0832PZCBLGI8